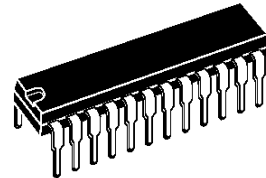


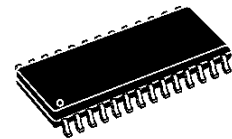
BUS-CONTROLLED AUDIO MATRIX

- 5 STEREO INPUTS
- 4 STEREO OUTPUTS
- GAIN CONTROL 0/2/4/6dB/MUTE FOR EACH OUTPUT
- CASCADABLE (2 different addresses)
- SERIAL BUS CONTROLLED
- VERY LOW NOISE
- VERY LOW DISTORSION



SHRINK24
(Plastic Package)

ORDER CODE : TEA6420



SO28
(Plastic Micropackage)

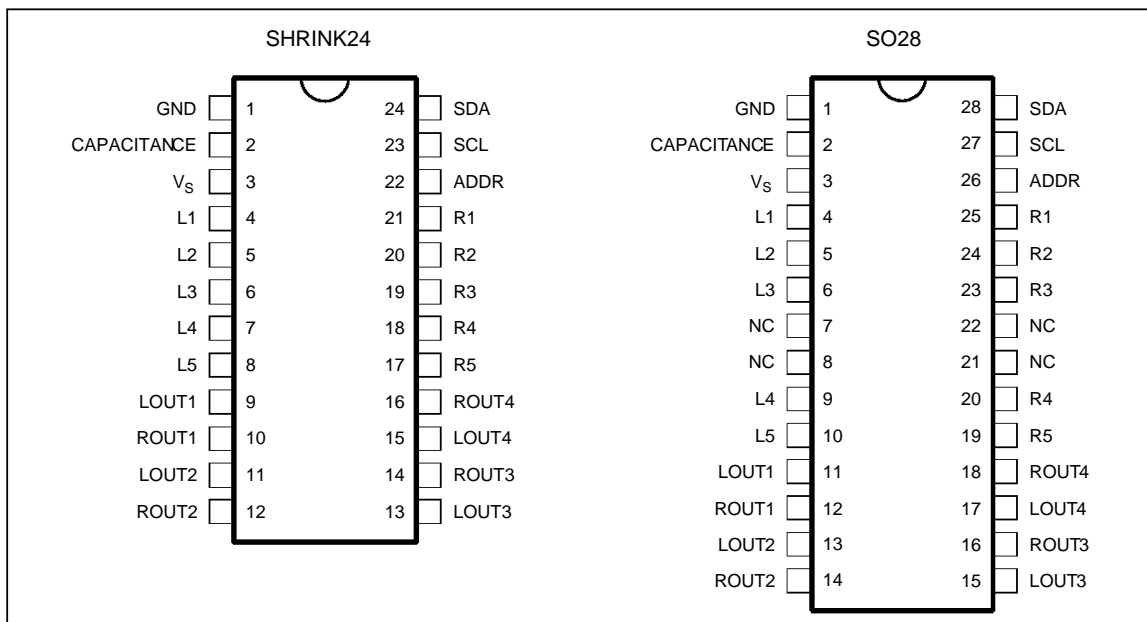
ORDER CODE : TEA6420D

DESCRIPTION

The TEA6420 switches 5 stereo audio inputs on 4 stereo outputs.

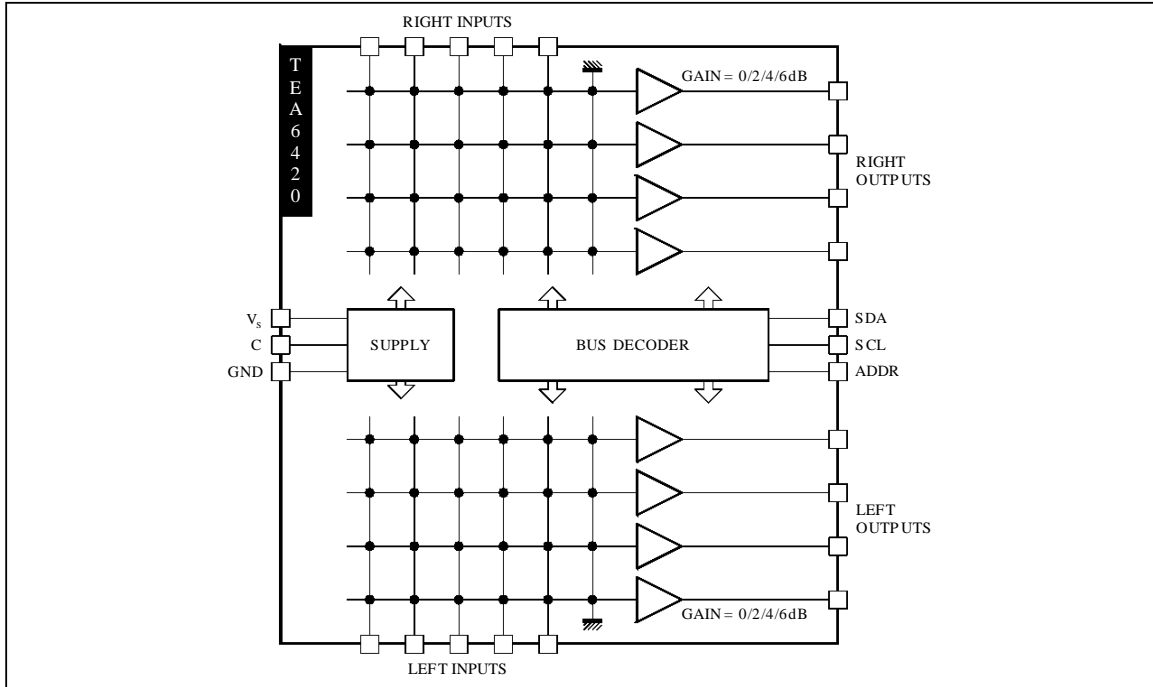
All the switching possibilities are changed through the I²C bus.

PIN CONNECTIONS



6420-01.EPS / 6420-02.EPS

BLOCK DIAGRAM



6420-03.EPS

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	Supply Voltage	10.2	V
T _{oper}	Operating Ambient Temperature	0, + 70	°C
T _{stg}	Storage Temperature	- 20, + 150	°C

6420-01.TBL

THERMAL DATA

Symbol	Parameter	Value	Unit
R _{th(j-a)}	Junction Ambient Thermal Resistance	SHRINK24 SO28 75 75	°C/W

6420-02.TBL

ELECTRICAL CHARACTERISTICS

T_A = 25°C, V_S = 10V, R_L = 10kΩ, R_G = 600Ω, f = 1kHz (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
SUPPLY						
V _S	Supply Voltage		8	9	10.2	V
I _S	Supply Current			5	8	mA
SVR	Ripple Rejection	V _{IN} = 500mV _{RMS} , BW = 20 - 20kHz	70	80		dB

MATRIX

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{IN}	Input DC Level		4.5	5	5.5	V
R _I	Input Resistance		30	50	100	kΩ
C _S	Channel Separation	V _{IN} = 2V _{RMS} f = 1kHz Gain = 0dB Gain = 6dB	80 70	90 82		dB dB

6420-03.TBL

ELECTRICAL CHARACTERISTICS (continued)

$T_A = 25^{\circ}\text{C}$, $V_S = 10\text{V}$, $R_L = 10\text{k}\Omega$, $R_G = 600\Omega$, $f = 1\text{kHz}$ (unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
--------	-----------	-----------------	------	------	------	------

OUTPUT BUFFER

V_{OUT}	Output DC Level		4.5	5	5.5	V
R_{OUT}	Output Resistance			70	200	Ω
e_{NI}	Input Noise	BW = 20 - 20kHz, flat		3		μV
S/N	Signal to Noise Ratio	$V_{IN} = V_{OUT} = 1V_{RMS}$		110		dB
G_{min}	Min. Gain		-1	0	+1	dB
G_{max}	Max. Gain		5	6	7	dB
d	Distortion	$V_{IN} = V_{OUT} = 1V_{RMS}$		0.01	0.05	%
V_{CL}	Clipping Level	d = 0.3%	2	2.5		V_{RMS}
R_L	Output Load Resistance		2			$\text{k}\Omega$

BUS INPUT

V_{IL}	Input Low Voltage				1.5	V
V_{IH}	Input High Voltage		3			V
I_I	Input Current		-10		10	μA
V_O	Output Voltage	$I_O = 3\text{mA}$; SDA Acknowledge pin			0.4	V
R_{pu}	ADDR Pullup Resistor	Note	40	50		$\text{k}\Omega$

Note : R_{pu} is an internal pull-up resistor connected between the address programming pin ADDR and the internal positive supply voltage. Leaving ADDR disconnected or "floating" allows it to become logic 1. Connecting ADDR externally to the GND pin forces it to logic 0.

SOFTWARE SPECIFICATION**1. Chip address**

Address	HEX	ADDR
1001 1000	98	0
1001 1010	9A	1

2. Data bytes

Output select								
X	0	0	G_1	G_0	I_2	I_1	I_0	Output 1
	0	1						Output 2
	1	0						Output 3
	1	1						Output 4
Input select								
X	Q_1	Q_0	G_1	G_0	0	0	0	Input 1
					0	0	1	Input 2
					0	1	0	Input 3
					0	1	1	Input 4
					1	0	0	Input 5
					1	0	1	Mute
Gain select								
X	Q_1	Q_0	0	0	I_2	I_1	I_0	Gain = 6 dB
			0	1				Gain = 4 dB
			1	0				Gain = 2 dB
			1	1				Gain = 0 dB

X = don't care

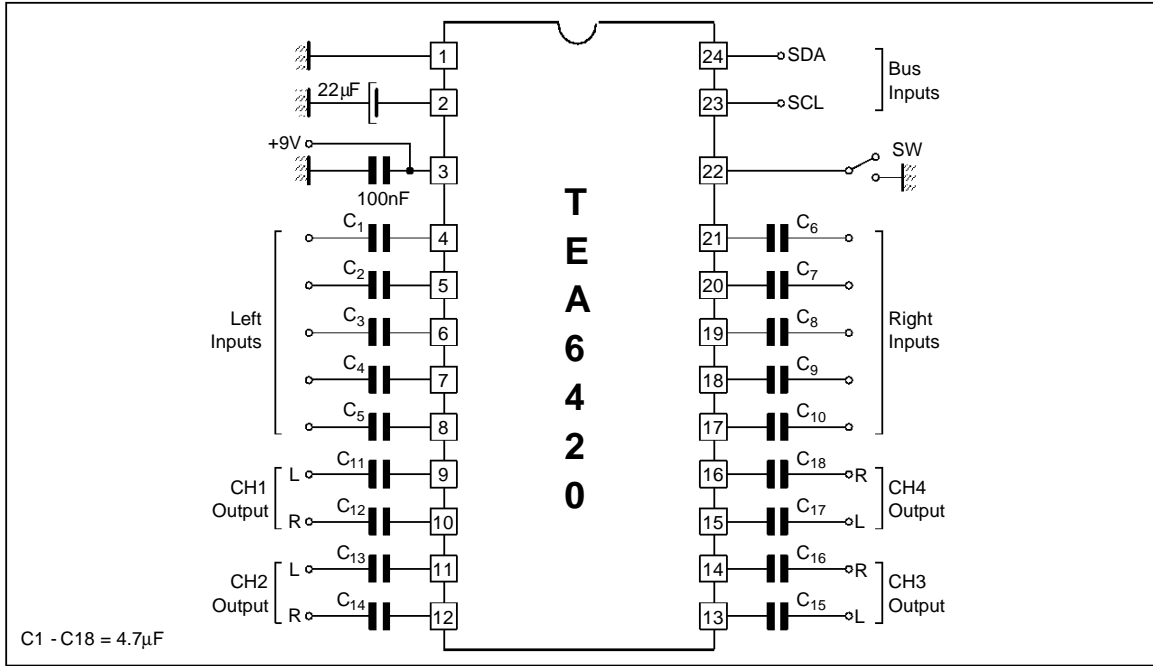
MSB is transmitted first

Example : 0 10 01 100 connects outputs 3 with input 5 at a gain of 4dB

The following are selected after power-on reset : input 5 selected for all outputs ; gain = 0dB.

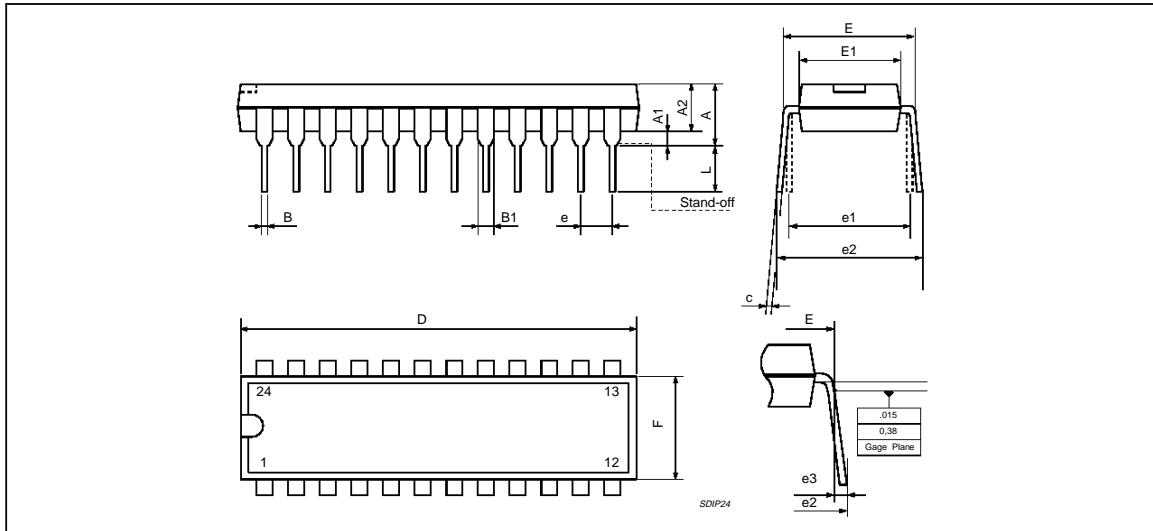
TEA6420

TYPICAL APPLICATION (DIP package)

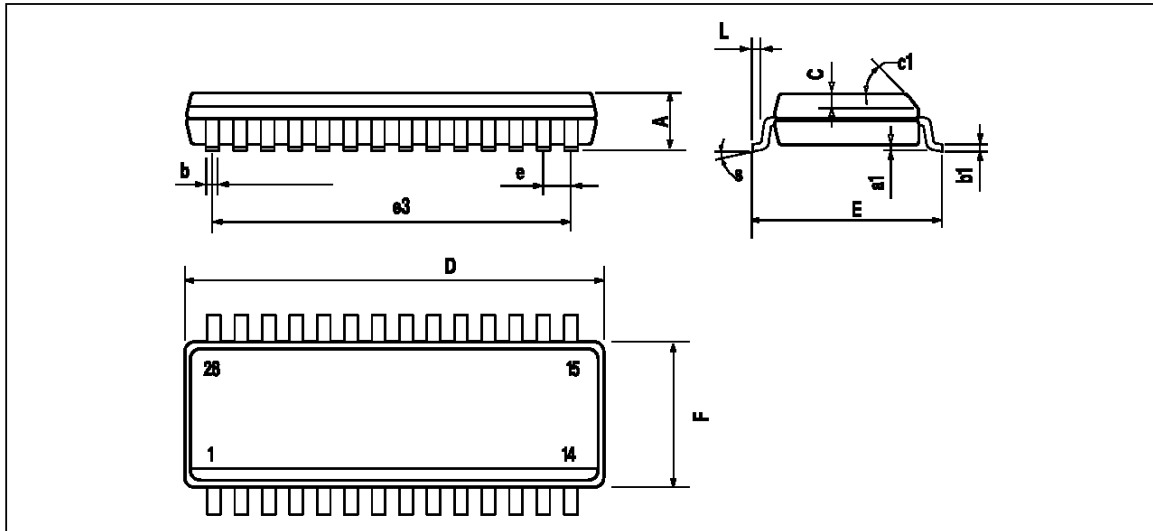


6420-04-EP/S

PACKAGE MECHANICAL DATA
24 PINS - PLASTIC SHRINK



Dimensions	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			5.08			0.20
A1	0.51			0.020		
	3.05	3.30	4.57	0.120	0.130	0.180
B	0.36	0.46	0.56	0.0142	0.0181	0.0220
B1	0.76	1.02	1.14	0.030	0.040	0.045
C	0.23	0.25	0.38	0.0090	0.0098	0.0150
D	22.61	22.86	23.11	0.890	0.90	0.910
E	7.62		8.64	0.30		0.340
E1	6.10	6.40	6.86	0.240	0.252	0.270
e		1.778			0.070	
e1		7.62			0.30	
e2			10.92			0.430
e3			1.52			0.060
L	2.54	3.30	3.81	0.10	0.130	0.150

PACKAGE MECHANICAL DATA
 28 PINS - PLASTIC MICROPACKAGE


PM-SC28.EPS

Dimensions	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			2.65			0.104
a1	0.1		0.3	0.004		0.012
b	0.35		0.49	0.014		0.019
b1	0.23		0.32	0.009		0.013
C		0.5			0.020	
c1	45° (Typ.)					
D	17.7		18.1	0.697		0.713
E	10		10.65	0.394		0.419
e		1.27			0.050	
e3		16.51			0.65	
F	7.4		7.6	0.291		0.299
L	0.4		1.27	0.016		0.050
S	8° (Max.)					

SC28.TBL

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